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Global Ceramics for Semiconductor Market 2026 by Company, Regions, Type and Application, Forecast to 2032

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Abstracts

According to our (Global Info Research) latest study, the global Ceramics for Semiconductor market size was valued at US$ 3512 million in 2025 and is forecast to a readjusted size of US$ 5652 million by 2032 with a CAGR of 6.9% during review period.

Ceramic materials for semiconductors mainly refer to various ceramic components used in semiconductor equipment.

Advanced engineering ceramic and quartz (fused silica) components and their coating systems are adopted to meet the requirements of high purity and cleanliness, corrosion/plasma resistance, resistance to high-temperature thermal cycling, dimensional stability, electrical insulation/thermal management, etc. Typical applications include: liners and ring components for plasma etching/deposition chambers, spray/gas distribution/insulation components, lift pins/clamping and handling components, support and guide components under vacuum conditions, as well as functional components such as ceramic heating/temperature control units and electrostatic chucks (ESCs).

In terms of material systems, ceramics for semiconductor equipment are mainly composed of high-purity oxide ceramics (Al?O?, Y?O?, ZrO?/ZTA, etc.) and non-oxide ceramics (AlN, SiC, Si?N?, BN/PBN, etc.). Their engineering-scale delivery is realized through the process chain of 'high-purity powder preparation ? shaping ? sintering/hot pressing/CVD ? precision machining ? ultra-clean cleaning ? (optional) coating/reconditioning'. On the trend front, on one hand, advanced process nodes and harsher plasma environments are accelerating the application of materials and coatings with higher corrosion resistance and lower particle generation (such as Y?O?/YOF systems and densified coating processes). On the other hand, in thermal management

and high-temperature processes, high thermal conductivity ceramic components for heating and bearing (such as AlN-based parts) are continuously increasing their market penetration.

Given the locations and importance of ceramic components in semiconductor equipment, their industrialization in the semiconductor field must meet stringent requirements in the following three aspects:

1. Advanced ceramic material performance: The materials must satisfy the comprehensive performance requirements of semiconductor equipment in terms of mechanical properties, thermal characteristics, dielectric properties, acid and alkali resistance, and plasma corrosion resistance.

2. Precision machining of hard and brittle difficult-to-machine materials: Advanced ceramic materials fall into the category of hard and brittle difficult-to-machine materials. Semiconductor equipment imposes high precision requirements on components, making machining one of the persistent bottlenecks restricting the application of ceramic components in semiconductor equipment.

3. Surface treatment of finished components: Since ceramic components in semiconductor equipment are usually closely arranged around wafers, and some even come into direct contact with wafers, the control of surface metal ions and particles is extremely strict. Post-machining surface treatment is therefore one of the key technologies for the application of ceramic components in semiconductor equipment.

The current status of the global market for ceramic components used in semiconductors can be summarized as small in scale yet highly critical, and strongly correlated with wafer fab capital expenditures and process complexity. These components are typically embedded as consumables, wear parts, or key functional components in the core chambers and transfer systems of front-end equipment (e.g., liners and ring components for plasma etching/deposition chambers, load-bearing, thermal insulation and electrical insulation parts, structural components for vacuum/chemical environments, etc.). Their demand is driven by two core factors: first, the cyclicality of wafer fab expansion and equipment investment; second, the increase in unit value and replacement frequency brought about by process upgrades. Taking 300mm wafer fabs as an example, SEMI forecasts that equipment spending for 300mm fabs will exceed USD 100 billion in 2025, with a cumulative expenditure of approximately USD 374 billion from 2026 to 2028. This directly boosts the demand for high-purity, plasma-resistant, low-particle ceramic structural components driven by both equipment installation volume and in-service maintenance needs on the equipment side.

In terms of key applications and competitive landscape, the most demanding use cases are concentrated in critical front-end equipment, including vacuum/insulation structural components for etching, various thin-film deposition, ion implantation, thermal processing/diffusion, and certain lithography-related processes, as well as high-purity wafer handling and load-bearing components. The industry is characterized by customized design, long validation cycles, and strong customer binding. In terms of competition, the global market has long been dominated by a small number of technical ceramics manufacturers with comprehensive capabilities in material systems, precision machining, and global delivery. Typical players include NGK Insulators, Kyocera, Niterra Co., Ltd., Coorstek, Ferrotec, TOTO Advanced Ceramics, Morgan Advanced Materials, and MiCo Ceramics Co., Ltd. In 2024, the top 8 global manufacturers accounted for 83% of the total market share. These companies provide customized products and process capabilities for semiconductor processing equipment, ranging from chamber liners/ring components to process chambers and various ceramic assemblies. For instance, Morgan publicly states that its semiconductor ceramic components cover applications such as Lithography, Implant, and CVD/PVD/Etch; NGK lists products including ceramic heaters, electrostatic chucks (ESCs), and chamber components made of AlN/Al?O?. In recent years, these manufacturers have expanded their capacities to meet growing demand?NGK, for example, has announced production expansion to cater to product requirements related to the next-generation semiconductor market. Overall, future industry differentiation will be primarily reflected in four core 'hard indicators': (1) plasma-resistant material systems and coating technologies; (2) ultra-high purity and low-particle control; (3) mass production of complex-shaped components with high consistency; (4) global local supply and rapid response capabilities.

From the perspective of growth trends and driving factors, the global market for semiconductor ceramic components is likely to exhibit steady growth alongside rising 300mm fab investment in the coming years, with simultaneous increases in unit value and consumption intensity. On one hand, in its latest 300mm Fab Outlook, SEMI predicts that global equipment spending for 300mm fabs will surpass USD 100 billion for the first time in 2025 (reaching approximately USD 107 billion), with cumulative spending hitting USD 374 billion from 2026 to 2028. The underlying drivers are clearly the surging demand for AI chips and the construction of regional/localized production ecosystems (focused on self-sufficiency and supply chain restructuring). Among these, logic/microprocessing chips (including sub-2nm, GAA, backside power delivery technologies, etc.) and memory chips (including HBM and 3D NAND) are the primary sources of investment and process upgrades. This means that the installation volume and utilization rate of critical equipment such as etching, thin-film deposition, thermal processing, cleaning, and ion implantation systems will continue to rise. Ceramic structural components are widely embedded in the core process chambers and key subsystems operating under harsh conditions (high temperature, high vacuum, strong plasma, and strong corrosion), such as chambers for Lithography, Implant, CVD/PVD/Etch applications, thus generating dual demand growth from initial equipment installation (BOM) and in-service maintenance (MRO). On the other hand, advanced processes impose increasingly stringent requirements on particle and metal contamination control, plasma erosion resistance, thermal stability, and thermal shock reliability. This has transformed ceramic structural components from 'general-purpose structural materials' into 'key factors influencing yield and equipment uptime', driving the iteration of material systems toward ultra-high purity alumina, aluminum nitride, silicon carbide, and high-purity sapphire. These materials are also combined with surface engineering technologies (coating, densification, cleaning) to reduce particle and contamination risks. For example, in wafer transfer and end-effector applications, ceramic transfer arms emphasize heat resistance and low wafer damage, with DLC coatings to enhance contamination resistance and anti-diffusion performance; in high-temperature and high-plasma environments, ultra-high purity materials are prioritized to improve plasma tolerance and low-particle characteristics; in chamber thermal management and clamping control systems, typical ceramic functional components such as electrostatic chucks and ceramic heaters highlight wide temperature range compatibility, corrosion resistance, low-particle processing, and temperature uniformity achieved through high thermal conductivity materials (e.g., AlN) to minimize metal contamination.

This report is a detailed and comprehensive analysis for global Ceramics for Semiconductor market. Both quantitative and qualitative analyses are presented by company, by region & country, by Type and by Application. As the market is constantly changing, this report explores the competition, supply and demand trends, as well as key factors that contribute to its changing demands across many markets. Company profiles and product examples of selected competitors, along with market share estimates of some of the selected leaders for the year 2025, are provided.

Key Features:

Global Ceramics for Semiconductor market size and forecasts, in consumption value ($ Million), 2021-2032

Global Ceramics for Semiconductor market size and forecasts by region and country, in consumption value ($ Million), 2021-2032

Global Ceramics for Semiconductor market size and forecasts, by Type and by Application, in consumption value ($ Million), 2021-2032

Global Ceramics for Semiconductor market shares of main players, in revenue ($ Million), 2021-2026

The Primary Objectives in This Report Are:

To determine the size of the total market opportunity of global and key countries

To assess the growth potential for Ceramics for Semiconductor

To forecast future growth in each product and end-use market

To assess competitive factors affecting the marketplace

This report profiles key players in the global Ceramics for Semiconductor market based on the following parameters - company overview, revenue, gross margin, product portfolio, geographical presence, and key developments. Key companies covered as a part of this study include NGK Insulators, Kyocera, Ferrotec, TOTO Advanced Ceramics, Niterra Co., Ltd., ASUZAC Fine Ceramics, Japan Fine Ceramics Co., Ltd. (JFC), Maruwa, Nishimura Advanced Ceramics, Repton Co., Ltd., etc.

This report also provides key insights about market drivers, restraints, opportunities, new product launches or approvals.

Market segmentation

Ceramics for Semiconductor market is split by Type and by Application. For the period 2021-2032, the growth among segments provides accurate calculations and forecasts for Consumption Value by Type and by Application. This analysis can help you expand your business by targeting qualified niche markets.

Market segment by Type

Alumina Ceramics

AlN Ceramics

SiC Ceramics

Silicon Nitride Ceramics

Others

Market segment by Application

Thin Film Deposition Equipment

Etching Equipment

Lithography Equipment

Ion Implanter

Thermal Processing Equipment

CMP Equipment

Wafer Handling Equipment

Packaging and Testing Equipment

Other Semiconductor Equipment

Market segment by players, this report covers

NGK Insulators

Kyocera

Ferrotec

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TOTO Advanced Ceramics

Niterra Co., Ltd.

ASUZAC Fine Ceramics

Japan Fine Ceramics Co., Ltd. (JFC)

Maruwa

Nishimura Advanced Ceramics

Repton Co., Ltd.

Pacific Rundum

Coorstek

3M

Bullen Ultrasonics

STC Material Solutions

Precision Ferrites & Ceramics (PFC)

Ortech Ceramics

Morgan Advanced Materials

CeramTec

Saint-Gobain

Schunk Xycarb Technology

Advanced Special Tools (AST)

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- MiCo Ceramics Co., Ltd.
- WONIK QnC
- Micro Ceramics Ltd
- Suzhou KemaTek, Inc.
- Shanghai Companion
- Sanzer (Shanghai) New Materials Technology
- St.Cera Co., Ltd
- Fountyl
- Hebei Sinopack Electronic Technology
- ChaoZhou Three-circle
- Fujian Huaqing Electronic Material Technology
- 3X Ceramic Parts Company
- Krosaki Harima Corporation
- Kallex Company,Ltd
- Shaanxi UDC Materials Technology
- AGC
- Coalition Technology

Market segment by regions, regional analysis covers

- North America (United States, Canada and Mexico)

Europe (Germany, France, UK, Russia, Italy and Rest of Europe)

Asia-Pacific (China, Japan, South Korea, India, Southeast Asia and Rest of Asia-Pacific)

South America (Brazil, Rest of South America)

Middle East & Africa (Turkey, Saudi Arabia, UAE, Rest of Middle East & Africa)

The content of the study subjects, includes a total of 13 chapters:

Chapter 1, to describe Ceramics for Semiconductor product scope, market overview, market estimation caveats and base year.

Chapter 2, to profile the top players of Ceramics for Semiconductor, with revenue, gross margin, and global market share of Ceramics for Semiconductor from 2021 to 2026.

Chapter 3, the Ceramics for Semiconductor competitive situation, revenue, and global market share of top players are analyzed emphatically by landscape contrast.

Chapter 4 and 5, to segment the market size by Type and by Application, with consumption value and growth rate by Type, by Application, from 2021 to 2032.

Chapter 6, 7, 8, 9, and 10, to break the market size data at the country level, with revenue and market share for key countries in the world, from 2021 to 2026.and Ceramics for Semiconductor market forecast, by regions, by Type and by Application, with consumption value, from 2027 to 2032.

Chapter 11, market dynamics, drivers, restraints, trends, Porters Five Forces analysis.

Chapter 12, the key raw materials and key suppliers, and industry chain of Ceramics for Semiconductor.

Chapter 13, to describe Ceramics for Semiconductor research findings and conclusion.

Contents

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6 NORTH AMERICA

7 EUROPE

8 ASIA-PACIFIC

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List Of Tables

LIST OF TABLES

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List Of Figures

LIST OF FIGURES

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